

3rd International Summer School on INtelligent Signal Processing for FrontIEr Research and Industry

Monday 14 September 2015 - Friday 25 September 2015

**Hamburg
Programme**

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Wednesday 16 September 2015

Introduction session on Advanced Very Deep Sub Micron CMOS technologies, 3D technologies and Industry trends - Auditorium III 2nd Floor (13:30-15:00)

Intelligent devices as those reviewed in the previous day lectures need compact and closely integrated Front-End processing. The micro-electronic engineers are thus challenged to use cutting-edge Very Deep Sub Micron (VDSM) technology and novel integration techniques for designing this new generation of Front-End circuits, both for the fundamental research and many areas in the applied life. This is a very exciting and fast evolving technology field, tackled by this session that will also show how high tech and Fundamental Physics Research are closely linked here.

time	title	presenter
13:30	VERTICAL INTEGRATION in NEW DEVICES	JONES, Matthew

Wednesday 23 September 2015

Introduction session on Advanced Very Deep Sub Micron CMOS technologies, 3D technologies and Industry trends - Auditorium III 2nd Floor (11:00-13:00)

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time	title	presenter
11:00	VDSM...HOW DEEP ? : benefits and limitations	DEPTUCH, Grzegorz